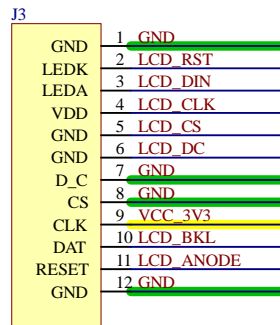
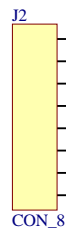
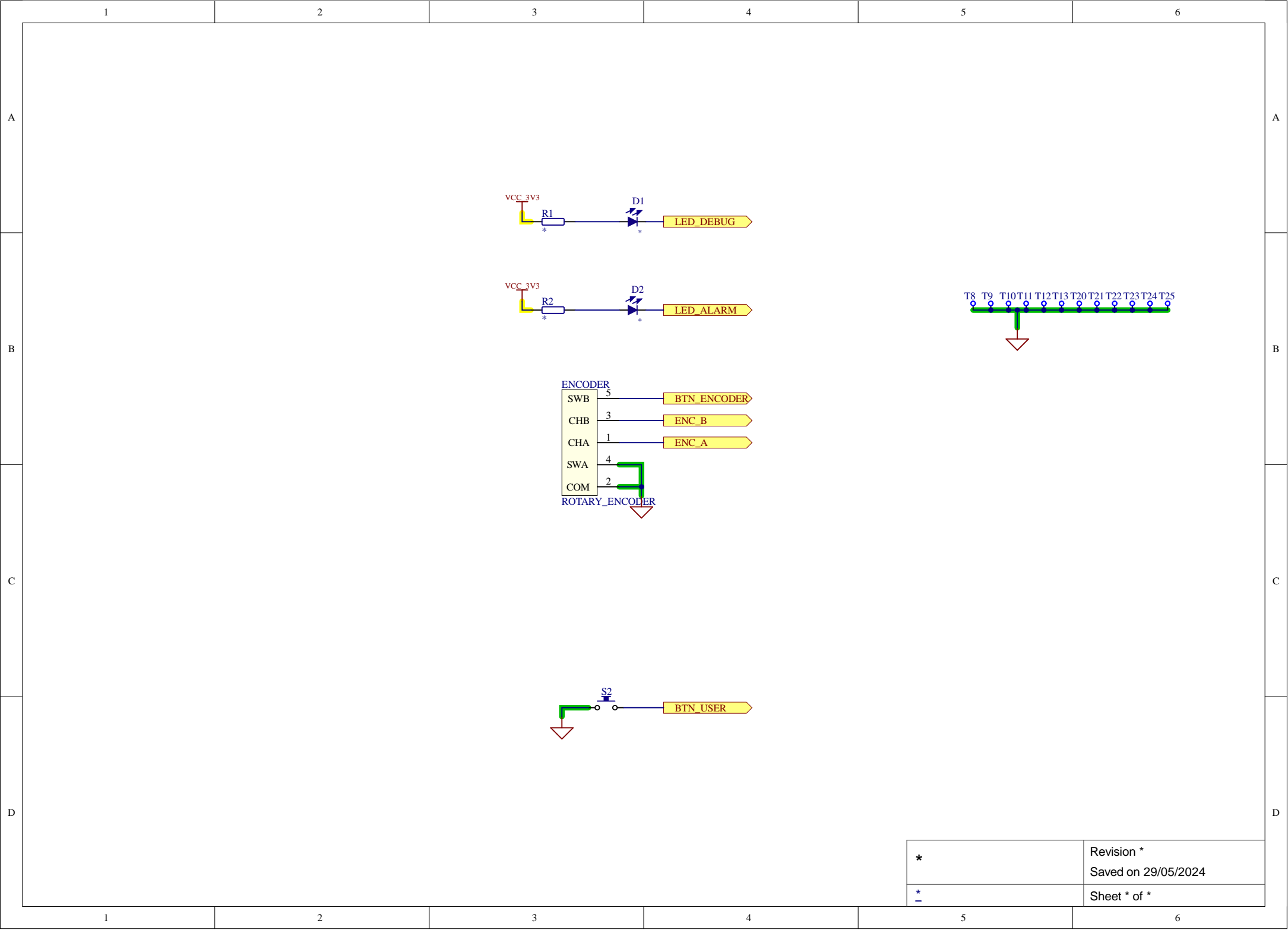


| | |
|--|-----------------------------------|
| Wifi Alarm Clock | Revision 1 Saved on 27/05/2024 |
| skilbeck.com | Sheet 1 of 1 |



| 1 | 2 | 3 | 4 | 5 | 6 |
|---|---|---|---|---|---|
|---|---|---|---|---|---|



Design Rules Verification Report

Filename : E:\dev\wifi_alarm_clock\pcbs\devkit\alarm_clock_devkit\alarm_clock_devkit.Prj

Warnings 0
Rule Violations 0

| Warnings | |
|----------|---|
| Total | 0 |

| Rule Violations | |
|---|---|
| Clearance Constraint (Gap=0.508mm) (InNetClass('POWER24') And ((IsPad And (InNet('GND') Or InNet('VCC_LED')) | 0 |
| Clearance Constraint (Gap=-0.1mm) (InPadClass('AGND_TIE')), (InNet('GND') And OnBottomLayer | 0 |
| Clearance Constraint (Gap=0.127mm) (All), (All) | 0 |
| Clearance Constraint (Gap=0.2mm) (All), (IsKeepOut | 0 |
| Short-Circuit Constraint (Allowed=No) (All), (All) | 0 |
| Short-Circuit Constraint (Allowed=Yes) (InPadClass('AGND_TIE')), (InNet('GND') | 0 |
| Un-Routed Net Constraint ((All)) | 0 |
| Modified Polygon (Allow modified: No), (Allow shelved: No) | 0 |
| Width Constraint (Min=0.127mm) (Max=1.27mm) (Preferred=0.127mm) (All | 0 |
| Routing Layers(All) | 0 |
| Routing Via (Templates Used To Check Via: GND_VIA, POWER_VIA) (All | 0 |
| Power Plane Connect Rule(Relief Connect)(Expansion=0.508mm) (Conductor Width=0.127mm) (Air Gap=0.127mm | 0 |
| Minimum Annular Ring (Minimum=0.13mm) (IsPad, | 0 |
| Minimum Annular Ring (Minimum=0.13mm) (IsVia, | 0 |
| Acute Angle Constraint [Tracks Only] (Minimum=45.000) (All, | 0 |
| Hole Size Constraint (Min=0.3mm) (Max=3mm) (All, | 0 |
| Hole To Hole Clearance (Gap=0.2mm) (All), (All) | 0 |
| Minimum Solder Mask Sliver (Gap=0.1mm) (All), (All) | 0 |
| Net Antennae (Tolerance=0mm) (All) | 0 |
| Board Clearance Constraint (Gap=0mm) (InLayerClass('Electrical Layers') | 0 |
| Component Clearance Constraint (Horizontal Gap = 0.1mm, Vertical Gap = Infinite) (All), (All) | 0 |
| Component Clearance Constraint (Horizontal Gap = 0mm, Vertical Gap = 0mm) (All), (InComponentClass('TestPoint') | 0 |
| Height Constraint (Min=0mm) (Max=25.4mm) (Preferred=12.7mm) (All | 0 |
| Total | 0 |

U1

J2

R8

T14

T15

T16

T17

T18

T19

J3

R11

C26

R9

C9

R10

C8

J4

R3

R1

R2

D1

D2

ENCODER

S2

IC2

IC1

C2

C1

C25

C3

C20

C11

R7

T26

T28

R4

C14

C21

Y1

C24

C22

C15

T2

T7

T3

T1

T4

T5

T6

C13

C23

C12

C16

C17

C19

C18

L

C7

C4

C5

U3

U

R

J1

M1

D3




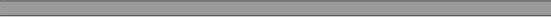






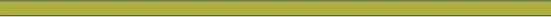
D4

R5

D5

T27

Board Stack Report

| Stack Up | | Layer Stack | | | |
|----------|---|----------------|----------|-----------|----------|
| Layer | Board Layer Stack | Name | Material | Thickness | Constant |
| 1 |  | Top Paste | | | |
| 2 |  | Top Overlay | | | |
| 3 |  | Top Solder | SM-001 | 0.025mm | 4 |
| 4 | | Top Layer | Copper | 0.035mm | |
| 5 |  | Dielectric 2 | PP-006 | 0.210mm | 4.1 |
| 6 |  | Layer 1 | Copper | 0.015mm | |
| 7 |  | Dielectric 1 | Core-043 | 1.065mm | 4.3 |
| 8 |  | Layer 2 | Copper | 0.015mm | |
| 9 |  | Dielectric 3 | PP-006 | 0.210mm | 4.1 |
| 10 |  | Bottom Layer | Copper | 0.035mm | |
| 11 | | Bottom Solder | SM-001 | 0.025mm | 4 |
| 12 |  | Bottom Overlay | | | |
| 13 |  | Bottom Paste | | | |
| | Height : 1.637mm | | | | |